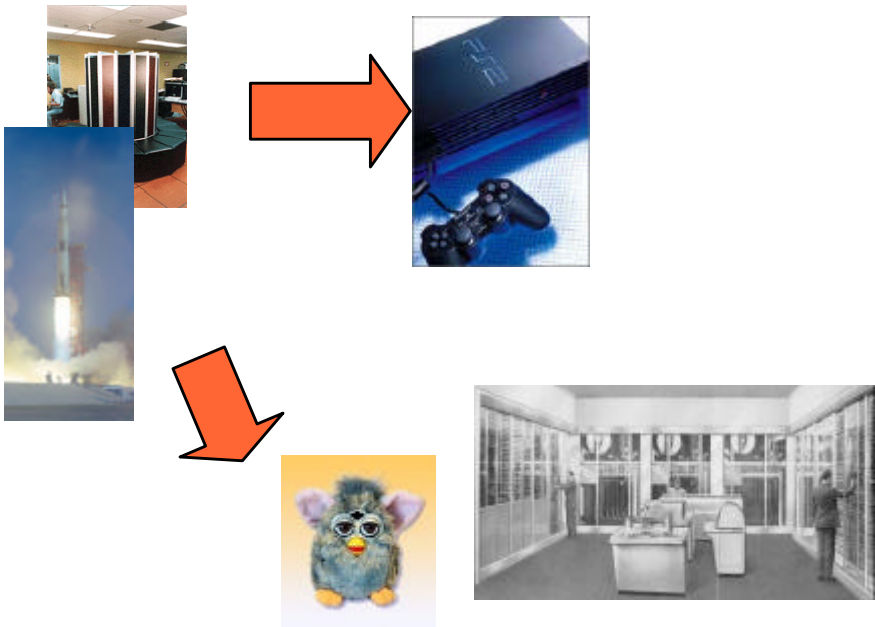


Reconfiguring The Future


Seth Copen Goldstein
Carnegie Mellon University
seth@cs.cmu.edu

IEE FPGA Developers Forum
10/22/03

Moore's Law


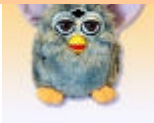


Moore's Law



Nanoscale components \Rightarrow Computers that are

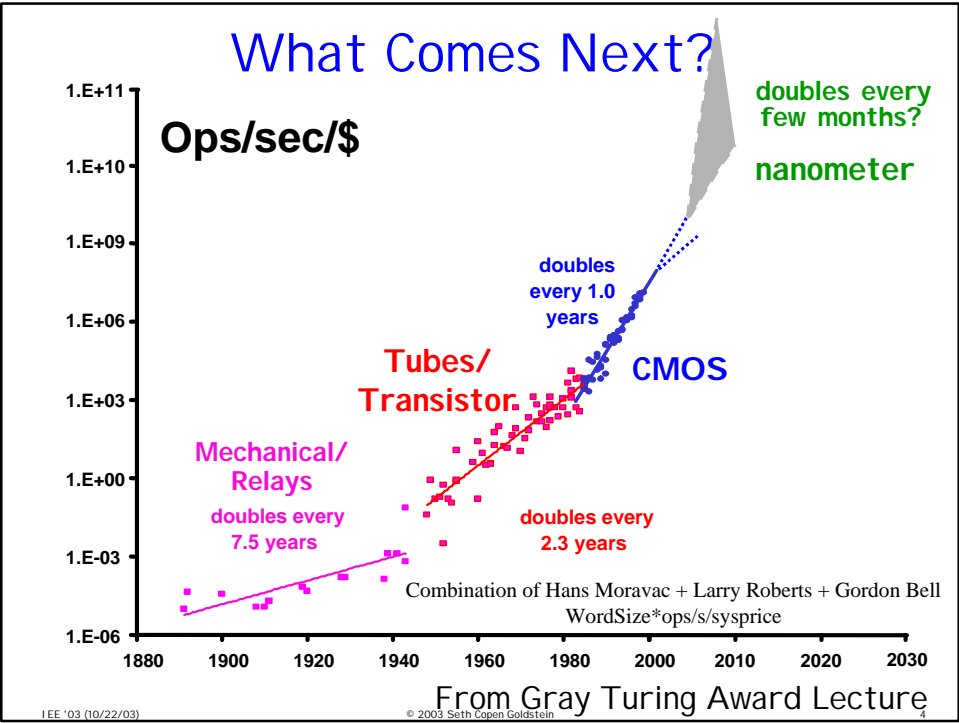
- *Small* enough to fit inside cells
- *Cheap* enough to be disposable
- *Dense* enough to embed a supercomputer
- *Smart* enough to assemble themselves



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3



Technology Shifts

- Size of Devices
⇒ Inches to Microns to **Nanometers**
- Type of Interconnect
⇒ Rods to Lithowires to **Nanowires**
- Method of Fabrication
⇒ Hammers to Light to **Self-Assembly**
- Largest Sustainable System
⇒ 10^1 to 10^8 to **10^{12}**
- Reliability
⇒ Bad to Excellent to **Unknown**

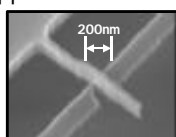
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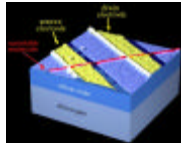
Size Matters

15nm FINFET,
end-of-roadmap
approx CMOS size



UC. Berkeley, MIT

Carbon Nanotube
transistor
~2nm width

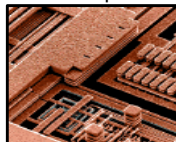


Delft

A trillion devices/cm²

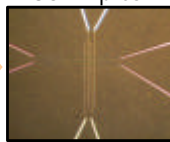
**... but many of them
probably won't work**

Copper wires,
predicted
~50nm pitch



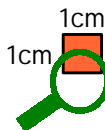
IBM

Nanowires,
Already
30nm pitch



HP/UCLA

**... and those that do
won't be identical**



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6

Independent of Technology

As we scale down:

• Devices become

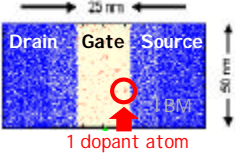
- more variable
- more faulty (defects & faults)
- numerous

• Fabrication becomes

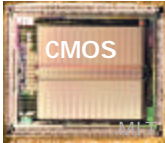
- More expensive
- More constrained

• Design becomes

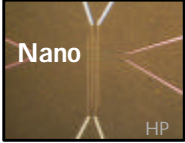
- More complicated
- More expensive



1 dopant atom



CMOS



Nano

HP

Requires:

- Defect tolerant architectures
- Higher level specification
- Universal substrate

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7

Independent of Technology

As we scale down:

• Devices become

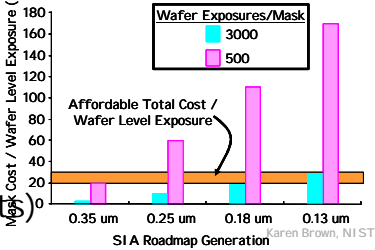
- more variable
- more faulty (defects & faults)
- numerous

• Fabrication becomes

- More expensive
- More constrained

• Design becomes

- More complicated
- More expensive



Wafer Exposures/Mask

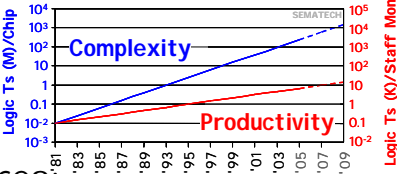
3000

500

Affordable Total Cost / Wafer Level Exposure

SIA Roadmap Generation

Karen Brown, NIST



Complexity

Productivity

Logic Ts (M)/Chip

Logic Ts (K)/Staff Mon

Requires:

- Defect tolerant architectures
- Higher level specification
- Universal substrate

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4

CMOS Too ...

- Precision is expensive
- Current Abstractions have a major impact on cost
 - Requires process engineers to deliver robust devices
 - Requires perfect devices
- Process rules and mask costs are already eliminating arbitrary patterns (e.g., forbidden pitches)
- CMOS: *just another nanoscale component*

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Manufacturing Paradigm Shift Required

TodayFuture

- Reliable Systems from reliable components
Reliable systems from unreliable components
- Functionality invested at time of manufacture
Functionality modified after manufacture
New manufacturing: Bottom-up assembly
- Behavior remains same as features scales down
Expect increased variability
Changes in functionality
Restrictions on connectivity

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10

Manufacturing Paradigm Shift Required

components

components

manufacture

manufacture

up assembly

scales down

d variability

functionality

connectivity

NanoRAM cell

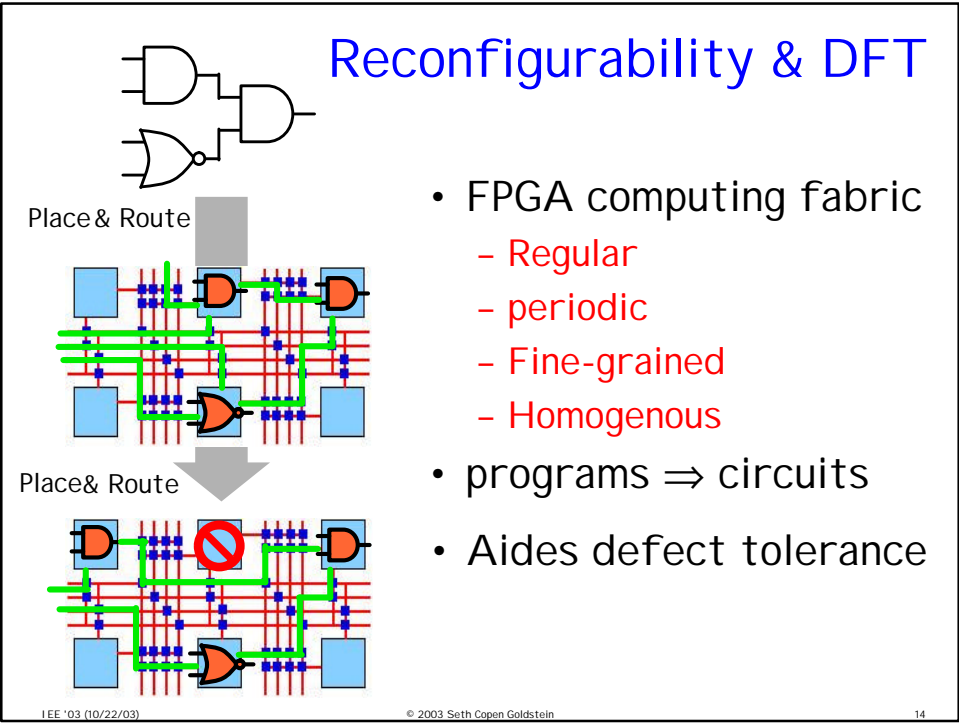
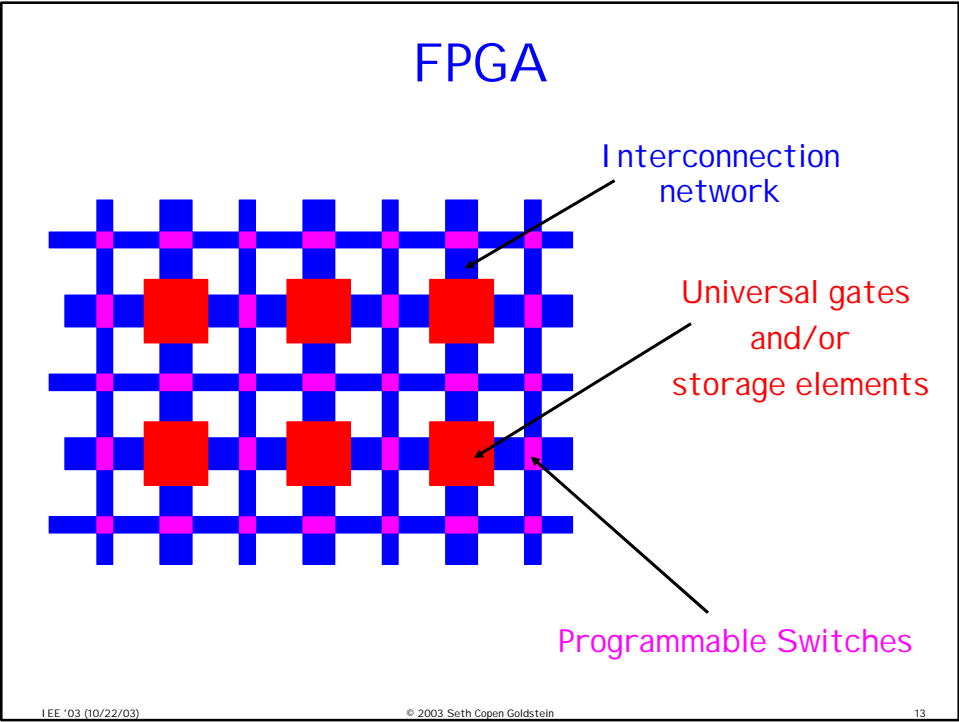
A CMOS RAM cell

I EE '03 (10/22/03) © 2003 Seth Copen Goldstein 11

Defect Tolerant Architectures

- Features:
 - Regular topology
 - Homogenous resources
 - Fine-grained?
 - Post-fabrication modification
- Example from today: DRAM
 - Requires external device for testing
 - Requires external device for repair
- Logic? **FPGA**

Key is redundancy



Defect Tolerance

Teramac works with mostly broken parts:

Defect mapping
+
Fine-grained configurability
⇒
Working device



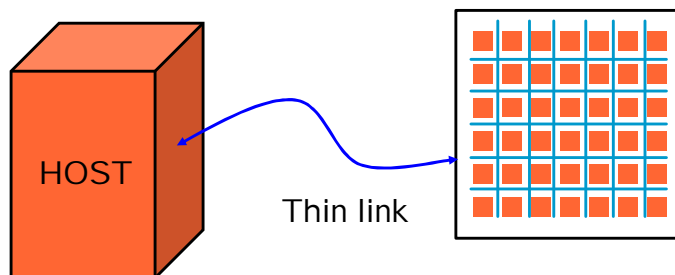
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Finding The Defects

- Need to discover the characteristics of the individual components, but
- Can't selectively stimulate or probe the components
- Download test machines

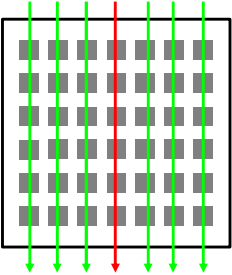


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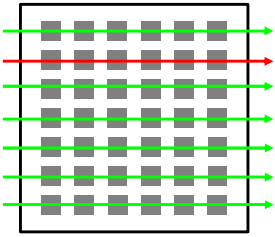
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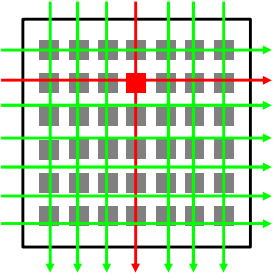
≈Built-In Self-Test



Configure testers vertically



Configure testers horizontally



I identify fault!

Configure the device to test itself!

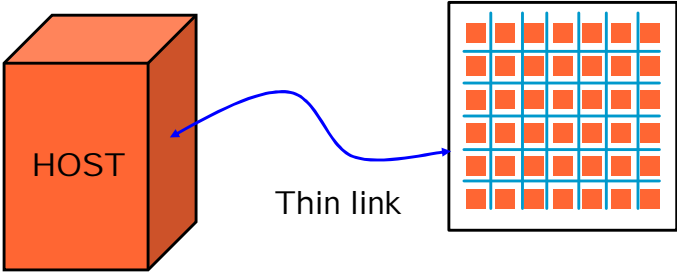
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Scaling to 10^{11}

- Eliminate Host
- After initial area is found, configure chip to act as host
- At end of complete test, upload entire defect map.
- For proposed device <1 day to map



Thin link

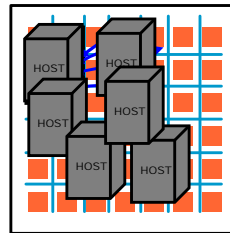
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18

Scaling to 10^{11}

- Eliminate Host
- After initial area is found, configure chip to act as host
- At end of complete test, upload entire defect map.
- For proposed device <1 day to map



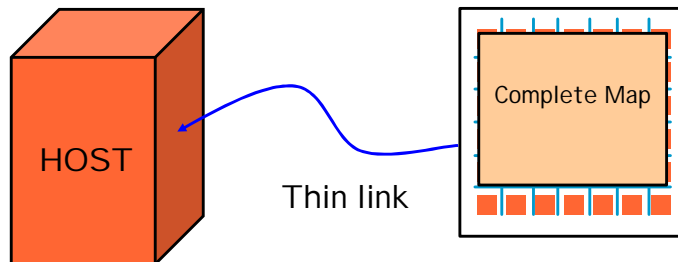
I EE '03 (10/22/03)

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19

Scaling to 10^{11}

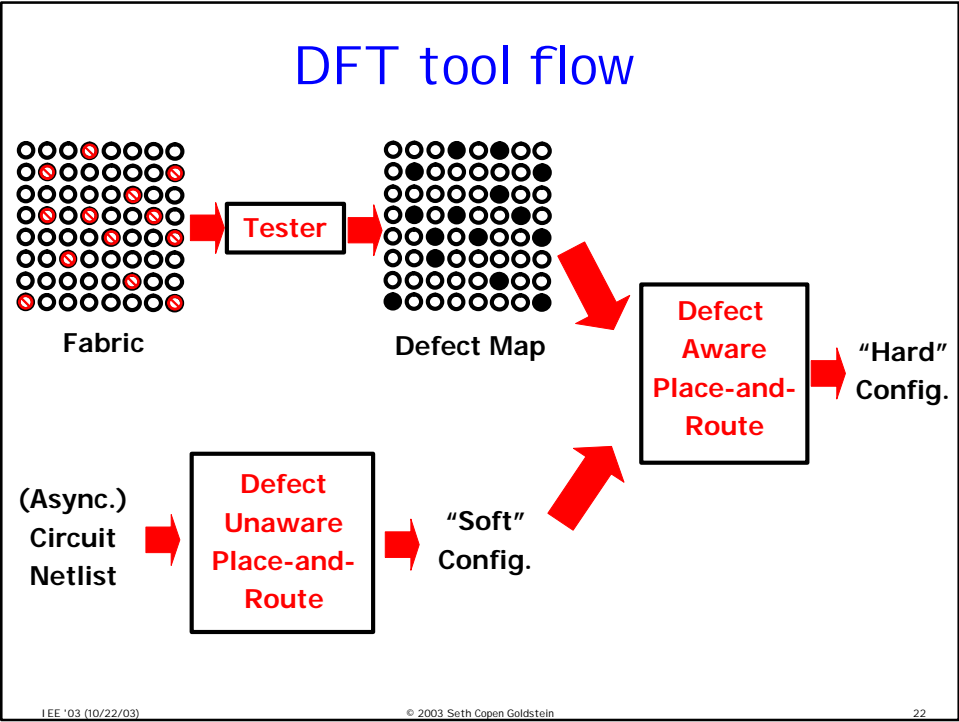
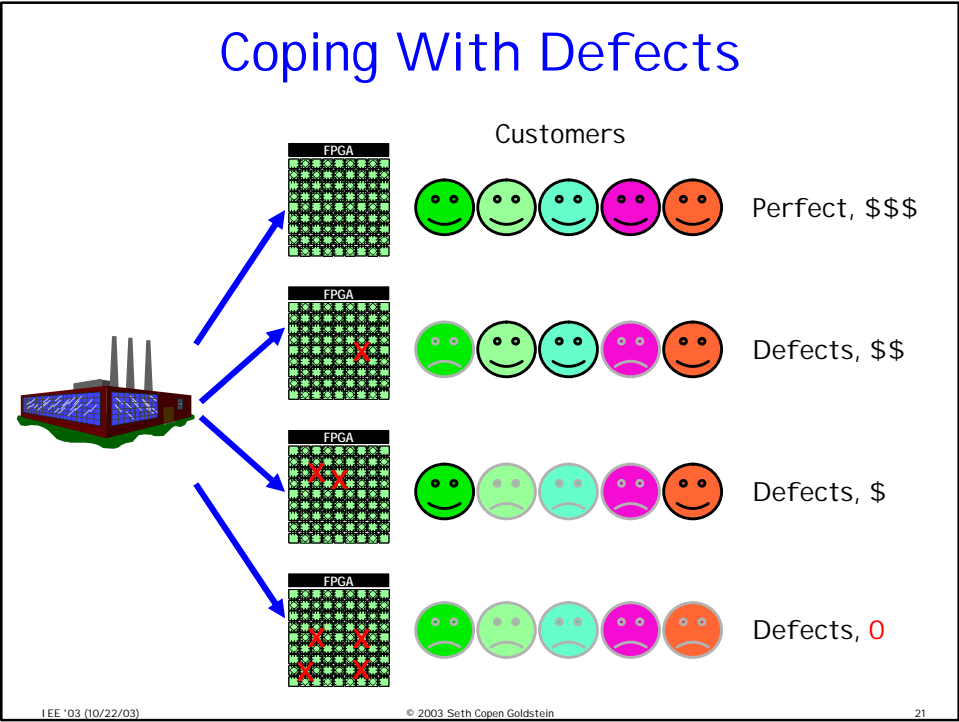
- Eliminate Host
- After initial area is found, configure chip to act as host
- At end of complete test, upload entire defect map.
- For proposed device <1 day to map



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Reconfigurable Computing

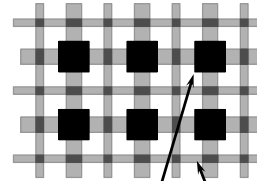
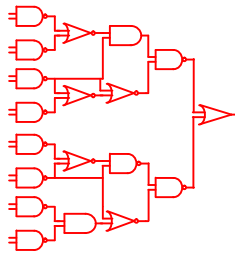
General-Purpose

Custom Hardware

General-Purpose
Custom Hardware

```
int reverse(int x)
{
    int k,r=0;
    for (k=0; k<64; k++)
        r |= x&1;
        x = x >> 1;
        r = r << 1;
    }
}
int func(int* a,int *b)
{
    int i,sum=0;
    for (i=0; *a!=0; i++)
        sum+=reverse(*a);
}
```

Compiler



Logic Blocks

Routing Resources

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Advantages of Reconfigurable

- Flexibility of a processor
 - Performance of custom hardware
- ^
Near

You have to

- Store and
- Address

the configuration

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Heart of an FPGA

a0

a1

0

0

0

1

data

a0

a1

a1 & a2

Universal gate =

data in

control

0

Switch controlled by a 1-bit RAM cell

The cost of the FPGA:
Increased Area - Delay Product

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Key Component: Reconfigurable Switch

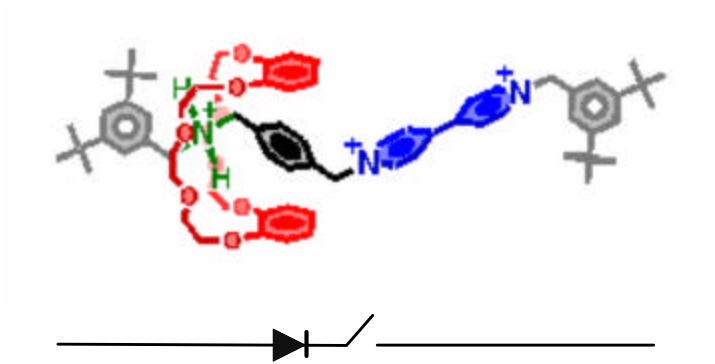
[2]Rotaxane
Molecular Switch

Complexation: Crown-Ammonium
Conditions: Neutral
Colour: Colourless

<http://www.chem.ucla.edu/dept/Faculty/stoddart/research/mv.htm>

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Key Component: Reconfigurable Switch

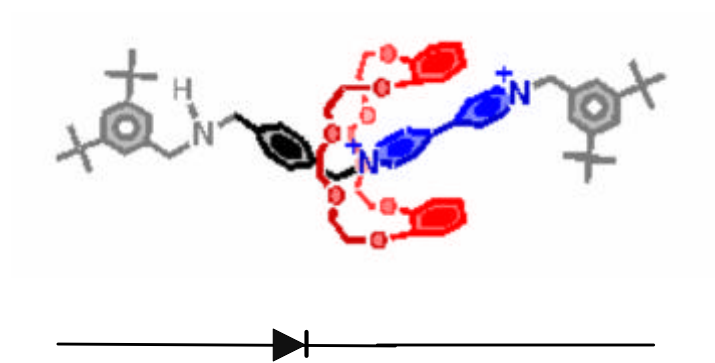


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27

Key Component: Reconfigurable Switch

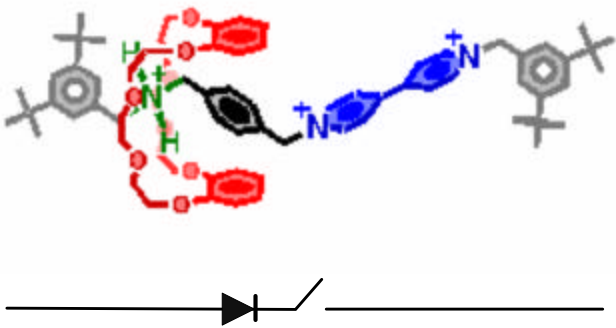


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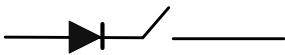
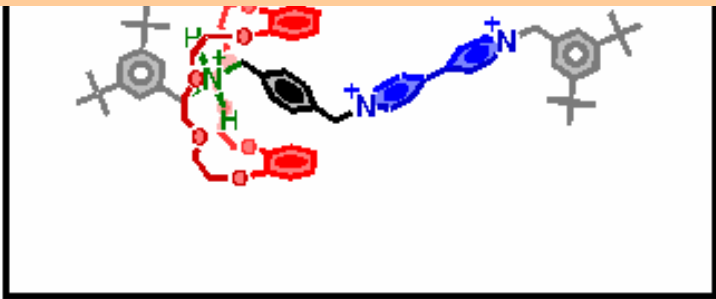
28

Key Component: Reconfigurable Switch

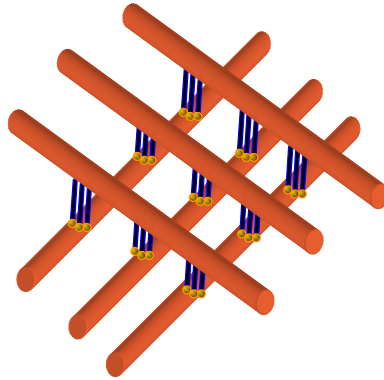


Key Component: Reconfigurable Switch

Reconfigurable Molecular Switch:
Eliminates overhead for reconfigurable
computing



The Molecular Electronics Advantage: A Reconfigurable Switch



- Each crosspoint is a reconfigurable switch
- Can be programmed using the signal wires

Eliminates overhead found in CMOS FPGAs!

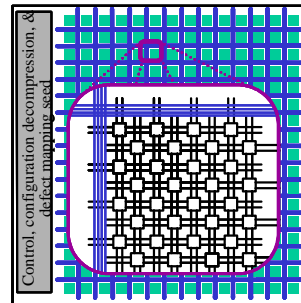
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Fabrication Is Different

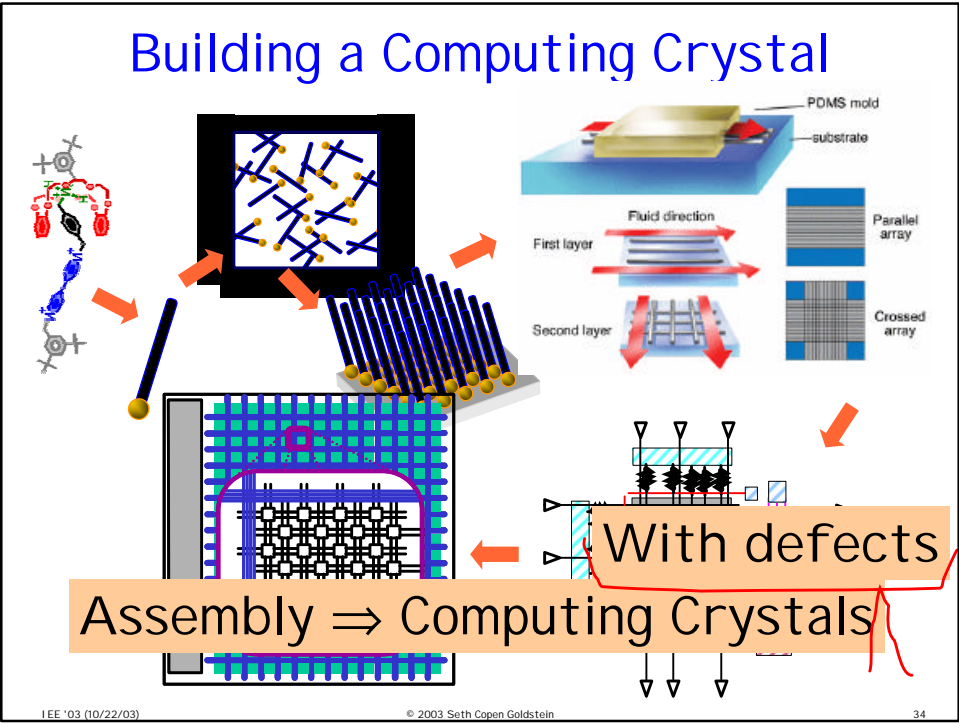
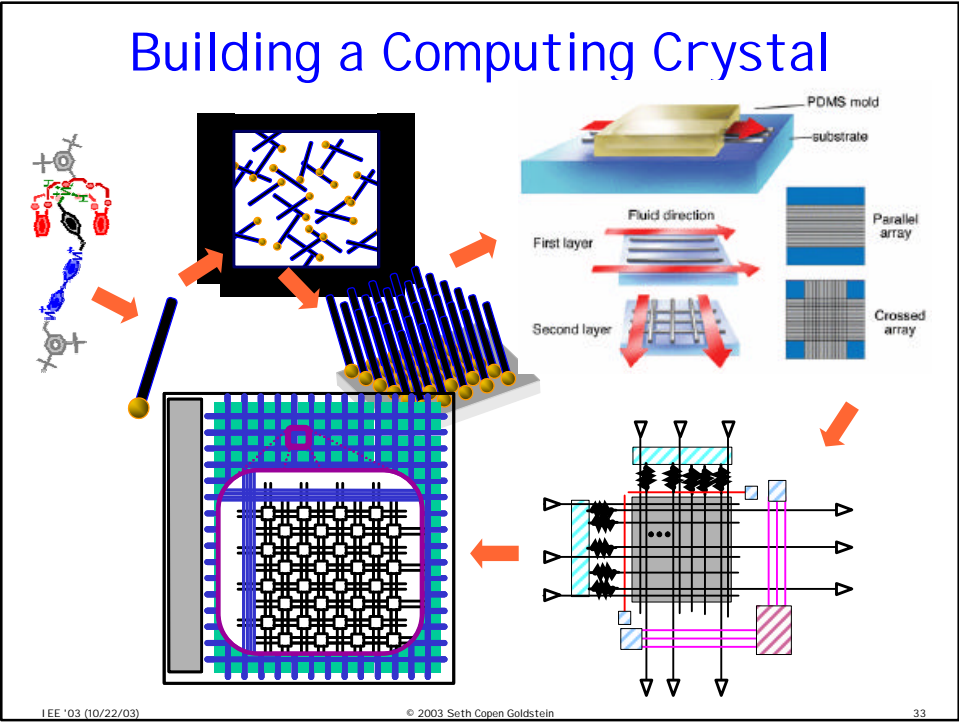
- Devices & wires alone are not useful
- Key to nanoscale computing is
bottom-up assembly



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Implications

- Use only 2 terminal devices?
- Only regular structures
- Defect-tolerance required
- Functionality must be added post-fabrication

→ Reconfigurable!

Remember, this all applies to future CMOS generations too!

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Reconfigurable Computing

General-Purpose

Custom Hardware

General-Purpose Custom Hardware

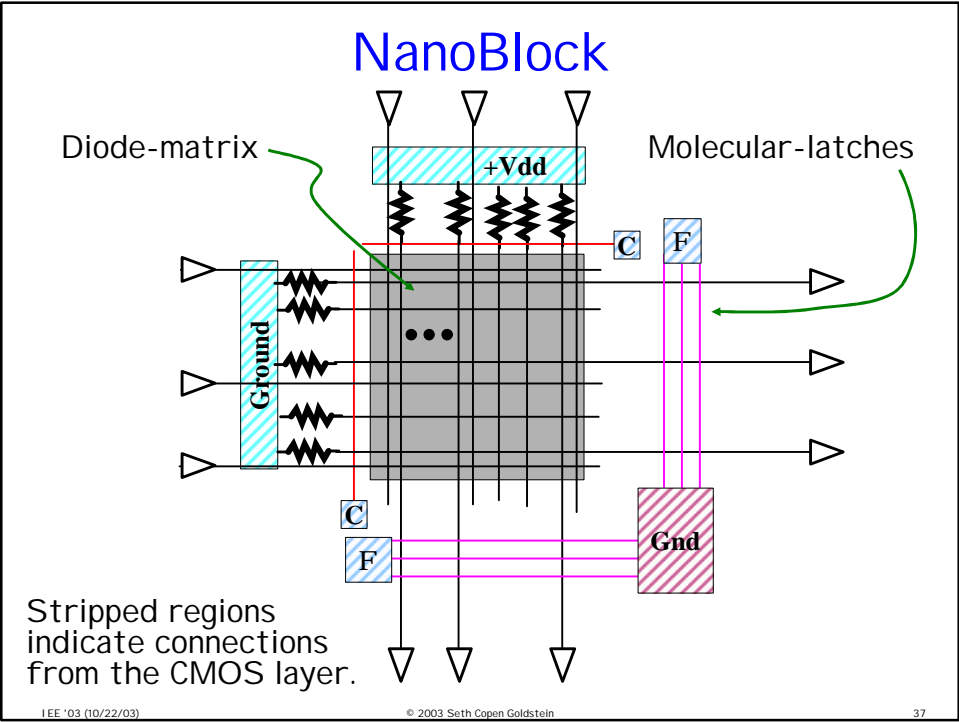
```
int reverse(int x)
{
    int k,x=0;
    for (k=0; k<64; k++)
        x |= x&1;
        x = x >> 1;
        x = x << 1;
    }
}
int func(int* a,int *b)
{
    int i,j,m,n;
    for (i=0; i<64; i++)
        for (j=0; j<64; j++)
            m = a[i] * b[j];
            n = m + n;
}
```

Compiler

Logic Blocks

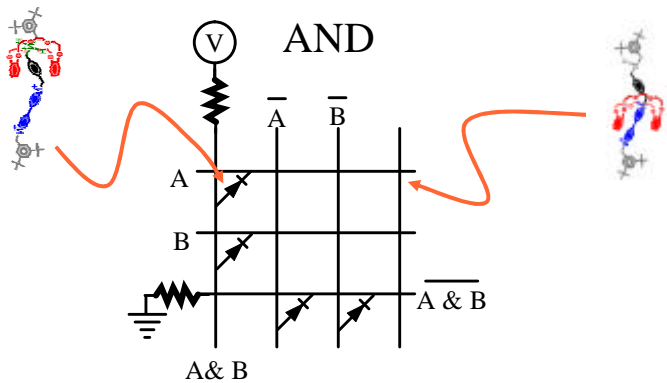
Routing Resources

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Computing with a nanoBlock

- The active component is a diode.
- Use diode-resistor logic



Diode-resistor Logic

Configured "ON"

Configured "OFF"

The diagram illustrates two configurations of a diode-resistor network. On the left, the 'Configured "ON"' state shows a voltage source V connected to a resistor, which is then connected to a grid of diodes. The diodes are arranged such that current can flow from the source through the grid to ground. On the right, the 'Configured "OFF"' state shows the same grid with a different connection, where current cannot flow. The grid is labeled with inputs A and B, and outputs \overline{A} , \overline{B} , and $\overline{A * B}$. The output $A * B$ is shown as the electrical equivalent of the nano-implementation.

Nano-implementation

Electrical equivalent

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How Do We Get There?

A landscape with a green hill, a blue sky with clouds, and a rainbow. A treasure chest filled with gold coins is on the right. A wavy line leads from a star on the left to the treasure chest. The text 'You are here' is next to the star.

You are here

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Abstractions Are The Key

- Transistor
 - An ideal switch and isolator
 - Identical all across the chip
- Circuit
 - Can be laid out on the chip
 - Manufactured without defects
- Instruction Set Architecture
 - Hides all details of the internal architecture
 - Mechanism for specifying programs

As Fabrication goes, so ...

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Necessary Device Abstraction

- Transistor provides it all
 - Switch
 - Fan-out
 - I/O isolation
 - Signal restoration

} Necessary for logic

} Necessary for large designs
- Replace single abstraction with multiple abstractions: SIRM
- Enables an incremental path to direct nano-circuits

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SIRM

- SIRM decomposes the abstraction into its fundamental components.
 - Switch
 - Isolation
 - Restoration
 - Memory
- SIRM already in use
- Allows circuit designers to explicitly manage the different components of a scalable circuit technology

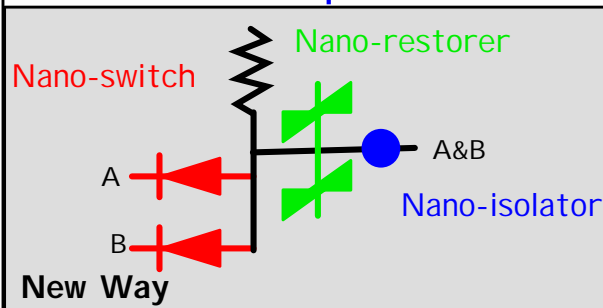
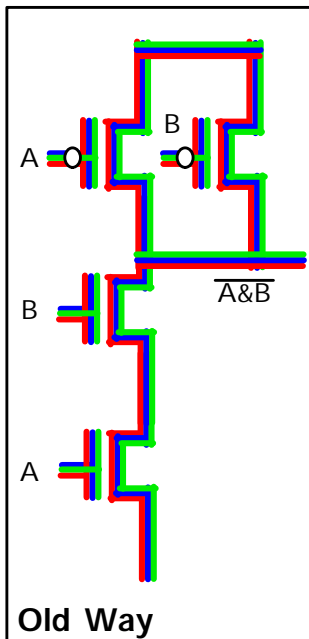
} Necessary for logic
 } Necessary for large designs

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SIRM Example

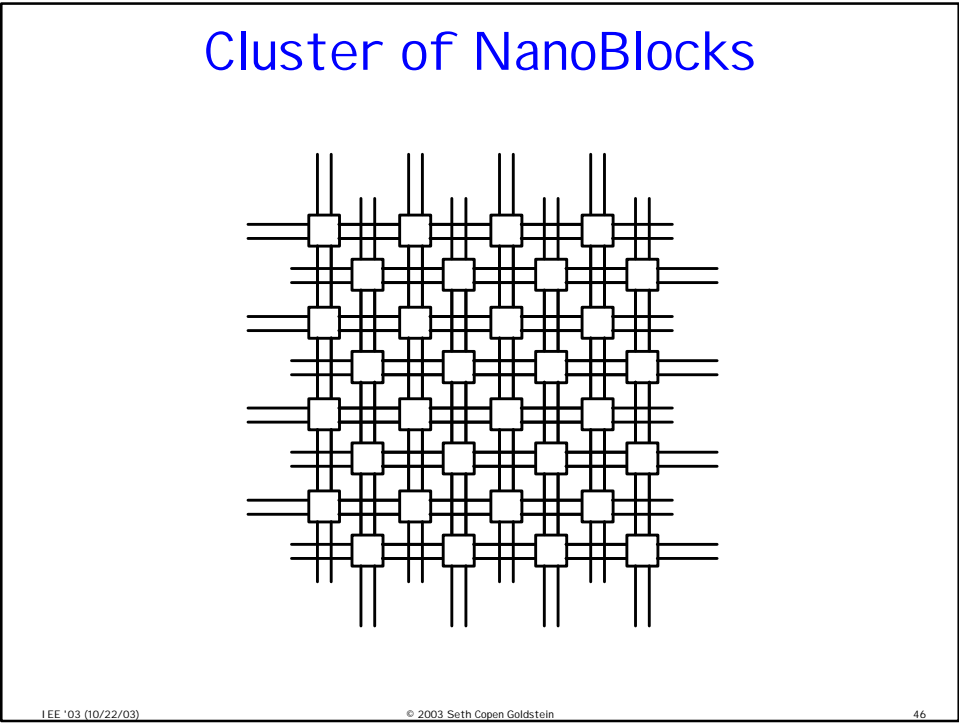
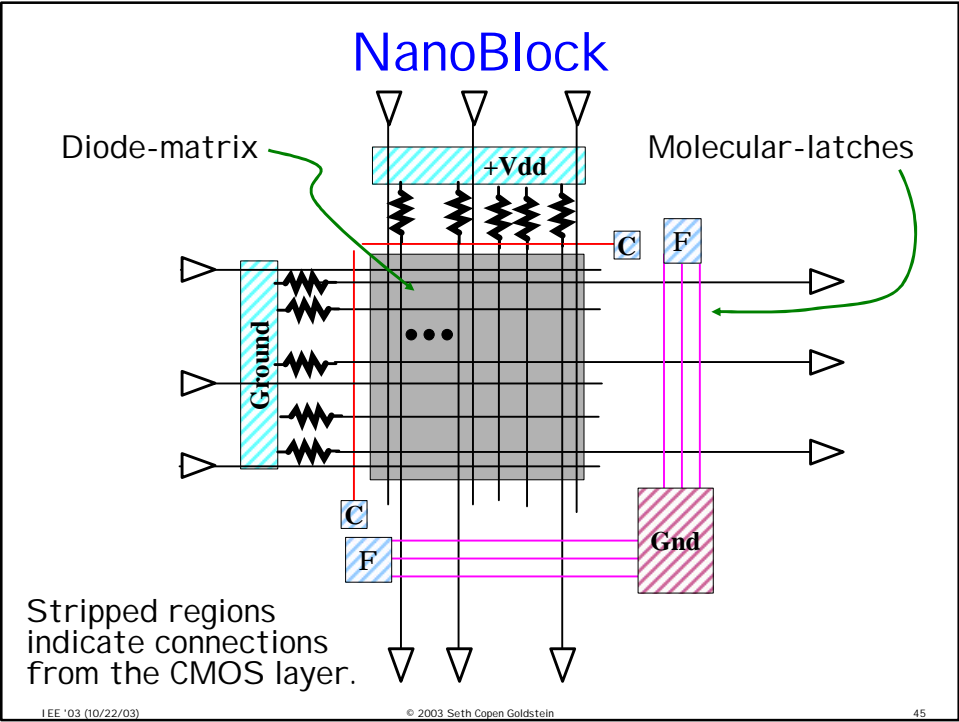


- Breaks up transistor abstraction into its components
- Allows creation of library of composable components
- Increases freedom of design

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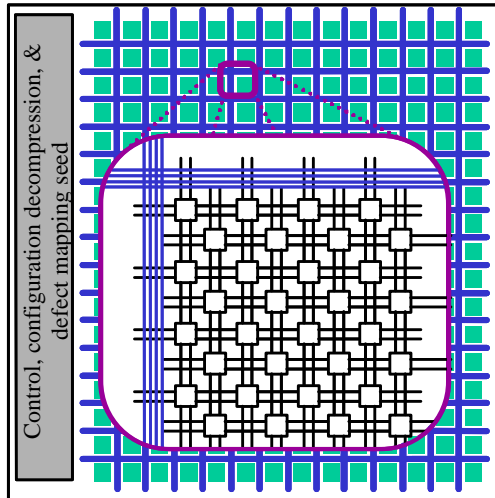
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The NanoFabric

- Nanoscale layer put **deterministically** on top of CMOS
- Highly regular
- $\sim 10^8$ long lines
- $\sim 10^6$ clusters
 - Cluster has 128 blocks



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NanoFabric Attributes

- Hierarchical fabrication
 1. Manufacture devices
 2. Non-deterministically align wires
 3. Self-assemble monolayers onto wires
 4. Create meshes
 5. Deterministically align w/CMOS
- Reconfigurable
- Defect tolerant

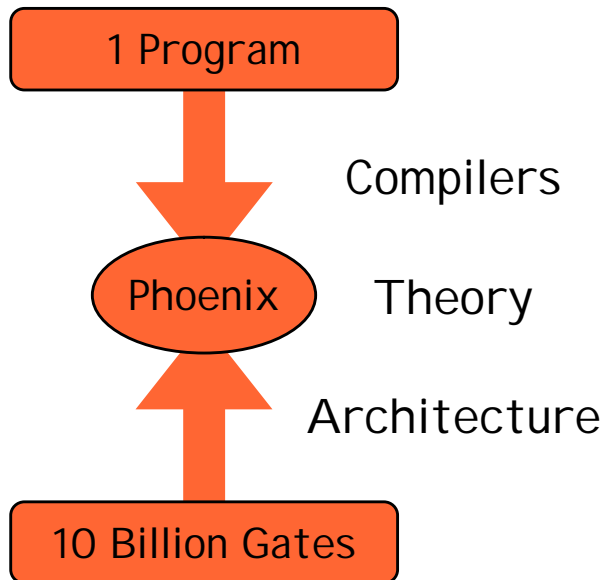
How do we use it?

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Spanning 10-orders of Magnitude



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Bryant's Law

- Processor verification is always 10 years behind
- What to do?

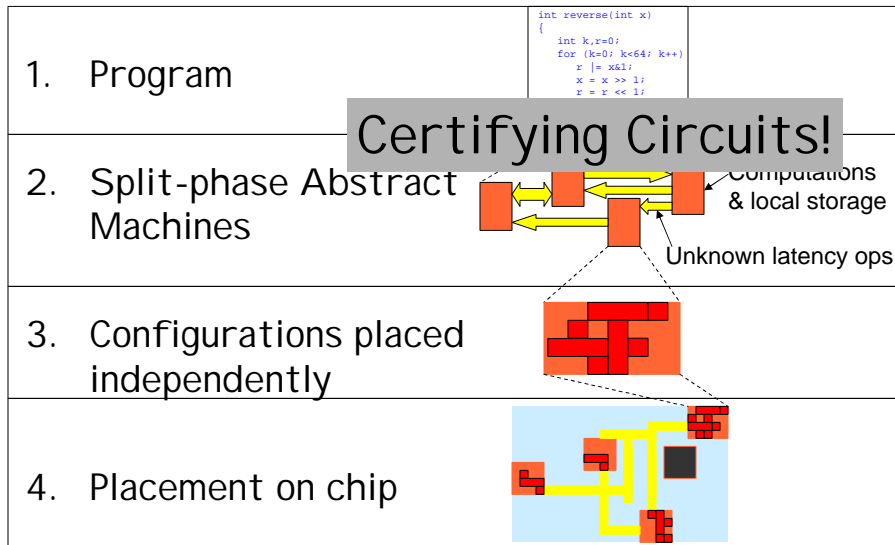
Don't use processors!

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Circuits From Compilers



Certifying Circuits!

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Phoenix

General: applicable to today's software

- programming languages
- applications

Automatic: compiler-driven

Scalable: - run-time: with clock, hardware
 - compile-time: with program size

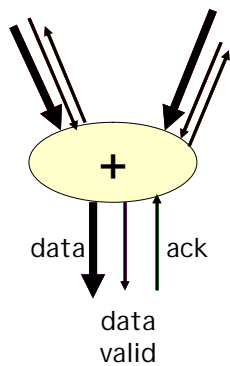
Parallelism: exploit application parallelism

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Asynchronous Computation



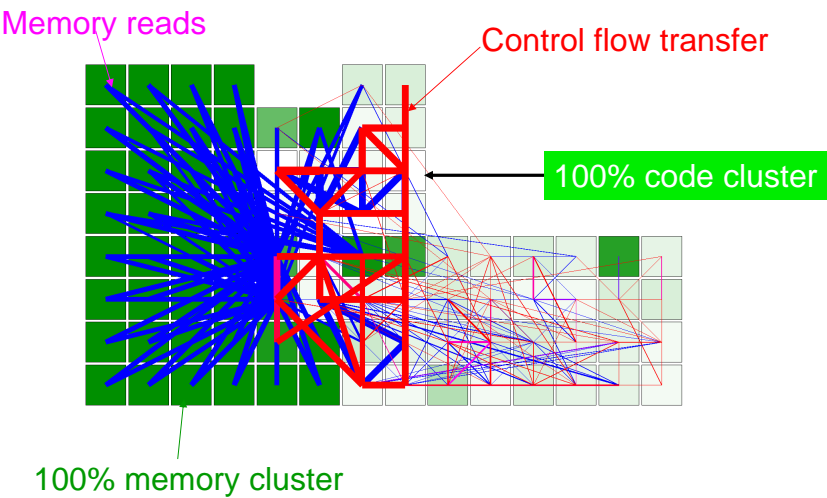
- Tolerant of
 - Layout
 - Parametric variation
 - Variable Latency Operations
- Low-power
- Natural implementation for dataflow

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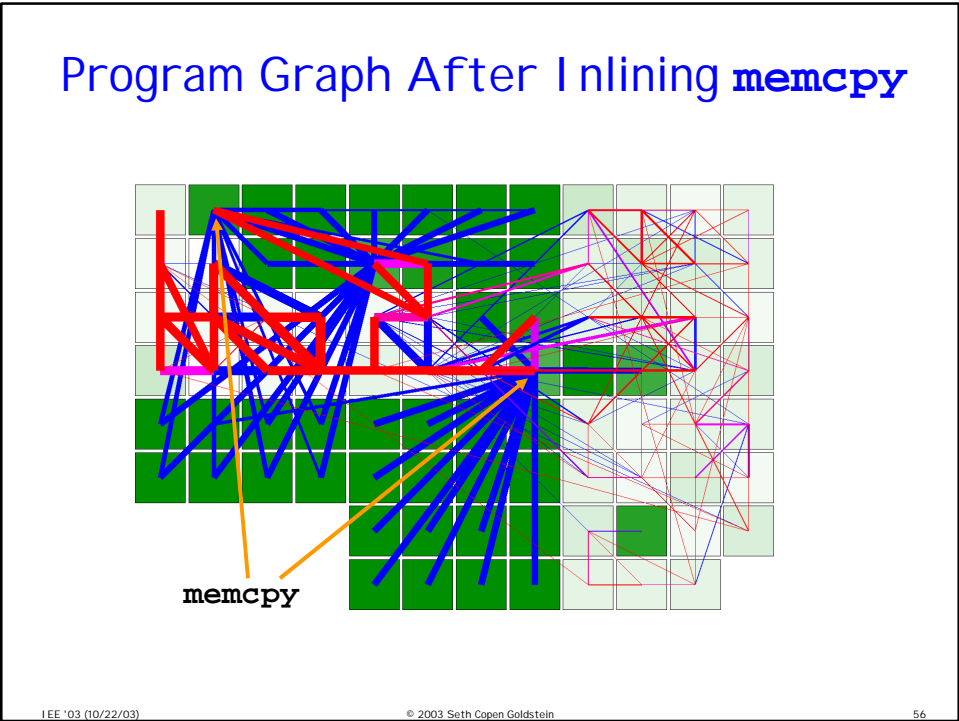
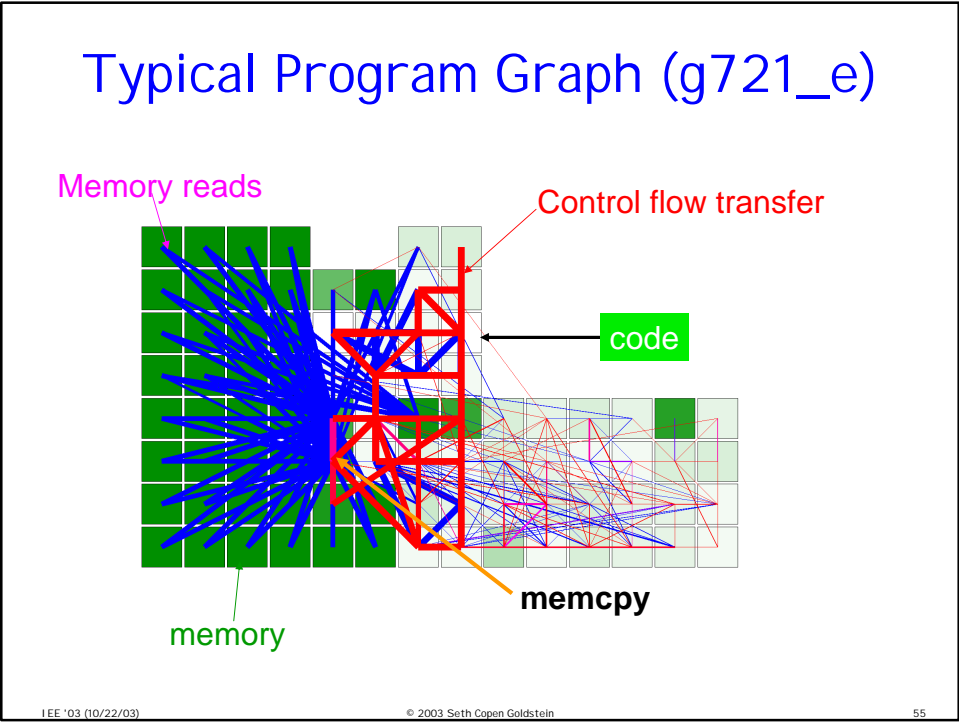
Typical Program Graph (g721_e)



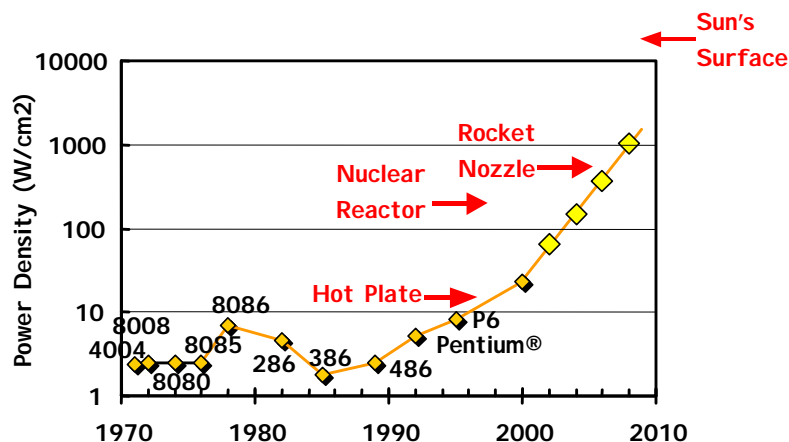
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Another Consideration: Power



□ Power densities too high to keep junctions at low temps

Source: Irwin & Borkar, De Intel

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Power $\propto 1/\text{Parallel}$

- $P \propto CV^2F$
- $F \propto \frac{(V-V_{th})^{5/4}}{V}$, for CMOS
- In relevant range: $F \propto V$
- So, $P \propto CF^3$
- Also, $1/A \propto T^n$, early VLSI theory result ($1 \leq n \leq 2$)
- If we fix T , then $F^{-1} \propto T$, $F \propto A^{-1/n}$
- If $n=2$, $P \propto CA^{-3/2}$
- If $C \propto A$, $P \propto A^{-1}$

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Conclusions

- Reconfigurable Computing is inevitable
 - Cost of manufacturing
 - Defect tolerance
 - Fabrication constraints
- Molecular switches are ideal for reconfigurable device
- EN: New constraints, but huge potential
 - Billions of devices per cm^2
 - Ultra-low power
 - Faster design time
 - Easier verification

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